

## 2 layers FPC 35µm with wet solder mask

Layer	Description	Stack-up	Thickness	Type
	Solder mask		15 µm	mask
Top L1	Copper RA		35 µm	Cu
	Glue		25,4 µm	epoxy
	Polyimid		25,4 µm	PI
	Glue		25,4 µm	epoxy
Bot L2	Copper RA		35 µm	Cu
	Solder mask		15 µm	mask
			<b>total thickness:</b>	<b>0,176 mm</b>
			<b>tolerance</b>	<b>10%</b>
			<b>maximum thickness</b>	<b>0,194 mm</b>
			<b>minimum thickness</b>	<b>0,159 mm</b>

## 2 layers FPC 35µm with cover lay

Layer	Description	Stack-up	Thickness	Type
	Solder mask		12,7 µm	mask
	Glue		12,7 µm	epoxy
Top L1	Copper RA		35 µm	Cu
	Glue		12,7 µm	epoxy
	Polyimid		12,7 µm	PI
	Glue		12,7 µm	epoxy
Bot L2	Copper RA		35 µm	Cu
	Glue		12,7 µm	epoxy
	Solder mask		12,7 µm	mask
			<b>total thickness:</b>	<b>0,159 mm</b>
			<b>tolerance</b>	<b>10%</b>
			<b>maximum thickness</b>	<b>0,175 mm</b>
			<b>minimum thickness</b>	<b>0,143 mm</b>

**NOTE:** The stack up may vary in order from the online calculation. Upper pictures are examples only.  
The selection of the solder mask or cover lay depends on the structures in the individual mask layer.  
For FPC orders in the online calculation LeitOn will chose between cover lay or solder mask without notification.  
It can also happen that top and bottom layer get different treatments!